Item	Qty	Reference	Description	Size	Value	MFR
1	1	C20	Capacitor, Ceramic,	0603	0.01uF/25V	STD
2	1	C44	Capacitor, Ceramic,	0603	1nF/50V	STD
3	1	C22	Capacitor, Ceramic,	0603	1uF/16V	STD
4	1	C1	Capacitor, Ceramic,	0603	3.3nF/50V	STD
5	1	C50	Capacitor, Ceramic,	0603	NA	STD
6	1	C7	CAP CER 1UF 35V X7R 0805	0805	1uF/35V	STD
7	1	C6	CAP CER 2.2UF 16V X7R 0805	0805	2.2uF/16V	STD
8	4	C2-5	CAP CER 4.7UF 25V X7R 0805	0805	4.7uF/25V	STD
9	1	J1	Connector, 100 mil Pitch			STD
10	1	D3	DIODE SML SIG 75V 0.15A SOD323F	SOD-323	1N4148WS	
11	1	U12	48V, 325mA Wide Vin Synchronous Step-down	WSON-8 LN	LM25018SD/NOPB	TI
			Regulator with Integrated MOSFETs		LIVIZ30163D/NOPB	11
12	1	T1	Transformer, MTC-0019SG			MNC
13	1	R3	Resistor, Chip, 1/10W, 1%	0603	10K	STD
14	1	R34	Resistor, Chip, 1/10W, 1%	0603	11K	STD
15	3	R1-2 R69	Resistor, Chip, 1/10W, 1%	0603	20K	STD
16	1	R5	Resistor, Chip, 1/10W, 1%	0603	12K	STD
17	1	R32	Resistor, Chip, 1/10W, 1%	0603	240K	STD
18	1	R33	Resistor, Chip, 1/10W, 1%	0603	68K	STD
19	1	R4	Resistor, Chip, 1/10W, 1%	0603	NA	STD
20	2	D1-2	DIODE SCHOTTKY 40V 0.4A SOD323	SOD-323	ZHCS400	Infineon
21	2	D4-5	Diode, Zener	SOD-323	NA	STD

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